MA27728

Silicon epitaxial planar type

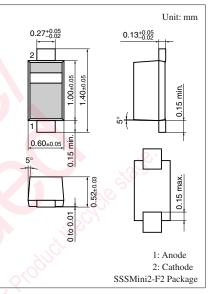
For switching circuits

Features

- High-density mounting is possible
- \bullet Low forward voltage V_F and good wave detection efficiency η
- Small temperature coefficient of forward characteristic
- Small reverse current I_R

Absolute Maximum Ratings $T_a = 25^{\circ}C$						
Parameter	Symbol	Rating	Unit			
Reverse voltage	V _R	30	V			
Maximum peak reverse voltage	V _{RM}	30	V			
Forward current	I _F	30	mA			
Peak forward current	I _{FM}	150	mA			
Junction temperature	Tj	125	°C			
Storage temperature	T _{stg}	-55 to +125	°C			

Absolute Maximum Ratings $T_a = 25^{\circ}C$



Marking Symbol: R

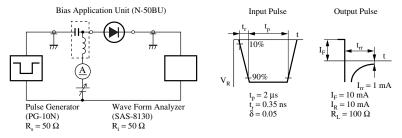
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _{F1}	$I_F = 1 \text{ mA}$	1 and the second s	95 T	0.4	V
	V _{F2}	$I_F = 30 \text{ mA}$	0	SO	1.0	
Reverse current	I _R	$V_R = 30 V$	- A	0	300	nA
Terminal capacitance	C _t	$V_R = 1 V, f = 1 MHz$	2.2	1.5		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 10 \text{ mA}$ $I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$		1.0		ns
Detection efficiency	η	$V_{IN} = 3 V_{(peak)}, f = 30 MHz$ $R_L = 3.9 k\Omega, C_L = 10 pF$		65		%

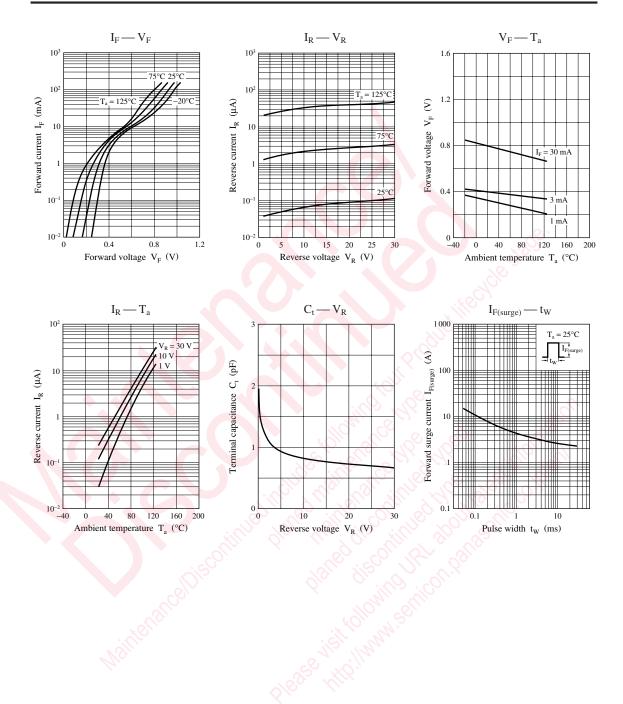
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

- 3. Absolute frequency of input and output is 2 GHz
- 4. *: t_{rr} measurement circuit



Panasonic



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